

(FILE 'USPAT' ENTERED AT 14:14:15 ON 15 DEC 1998)

L1 31652 S (IMAGE OR IMAGING) AND (SEMICONDUCTOR SUBSTRATE OR SEMIC
OND
L2 33406 S (DETECTOR CELLS OR IMAGE PIXELS OR PIXELS OR IMAGING CEL
LS)
L3 3534 S (ARRAY) (2A) (L2)
L4 1784 S (LOW TEMPERATURE BUMP? OR SOLDER? BUMP?)
L5 736 S L1 AND L3
L6 9 S L4 AND L5
L7 1537 S (READOUT CIRCUIT OR READOUT CELLS OR READOUT UNIT?)
L8 0 S L6 AND L7

=> d 16 1-9

1. 5,825,385, Oct. 20, 1998, Constructions and manufacturing processes for thermally activated print heads; Kia Silverbrook, 347/56 [IMAGE AVAILABLE]
2. 5,812,162, Sep. 22, 1998, Power supply connection for monolithic print heads; Kia Silverbrook, 347/58, 59 [IMAGE AVAILABLE]
3. 5,780,321, Jul. 14, 1998, LED display packaging with substrate removal and method of fabrication; Chan-Long Shieh, et al., 438/34, 26 [IMAGE AVAILABLE]
4. 5,723,866, Mar. 3, 1998, Method for yield and performance improvement of large area radiation detectors and detectors fabricated in accordance with the method; William J. Hamilton, Jr., 250/370.09, 370.01 [IMAGE AVAILABLE]
5. 5,650,640, Jul. 22, 1997, Integrated electro-optic package; John W. Stafford, et al., 257/81, 88, 734 [IMAGE AVAILABLE]
6. 5,621,225, Apr. 15, 1997, Light emitting diode display package; Chan-Long Shieh, et al., 257/81, 88, 99, 778, 779 [IMAGE AVAILABLE]
7. 5,583,350, Dec. 10, 1996, Full color light emitting diode display assembly; Michael P. Norman, et al., 257/88, 40, 89, 91, 99 [IMAGE AVAILABLE]
8. 5,497,258, Mar. 5, 1996, Spatial light modulator including a VLSI chip and using solder for horizontal and vertical component positioning; Teh-Hua Ju, et al., 349/58, 149 [IMAGE AVAILABLE]
9. 5,381,013, Jan. 10, 1995, X-ray **imaging** system and solid state detector therefor; John D. Cox, et al., 250/370.09, 366, 370.11 [IMAGE AVAILABLE]